



**iSBX™ 328 ANALOG OUTPUT  
MULTIMODULE™ BOARD  
HARDWARE REFERENCE MANUAL**

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HARDWARE REFERENCE MANUAL**

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I <sup>2</sup> -ICE	intelligent Programming	Library Manager	PROMPT
iCS	Inteltec	MCS	RMX/80
im	Intellink	Megachassis	RUPI
iMMX	iOSP	Micromainframe	System 2000
Insite	iPDS	Micromap	UPI

## PREFACE

This manual provides general information, preparation for use, programming information, principles of operation, and service information for the iSBX 328 Analog Output Multimodule Board. Supplementary information is provided in the following documents.

- Intel Peripheral Design Handbook, Order Number: 9800676
- Intel Multibus<sup>®</sup> Specification, Order Number: 9800683
- Intel iSBX<sup>™</sup> Bus Specification, Order Number: 142686
- Intel MCS-48 and UPI-41 Assembly Language Manual, Order Number: 9800255
- Intel UPI-41 Assembly Language Reference Card, Order Number: 9800871.
- Intel UPI-41A User's Manual, Order Number: 9800504.



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## CHAPTER 1. GENERAL INFORMATION

### 1-1. INTRODUCTION

The iSBX 328 Analog Output Multimodule Board is a member of Intel's growing family of expansion boards designed to allow quick, easy, and inexpensive expansion capability for the Intel single board computer product line. The iSBX 328 Analog Output Multimodule Board (hereafter referred to as the Multimodule board) provides the ability to add analog output capability to any host iSBC microcomputer that contains an iSBX bus connector. This manual contains the information required to use the Multimodule board, including chapters on general information, preparation for use, programming, principles of operation, and service information.

### 1-2. DESCRIPTION

The Multimodule board, shown in Figure 1-1, is designed to plug onto any host iSBC microcomputer that contains an iSBX bus connector. The board uses an 8041 UPI device to control eight analog output channels that may be user-configured via jumpers to operate in bipolar voltage output mode (-5 to +5 volts), unipolar voltage output mode (0 to +5 volts), or current loop output mode (4 to 20 mA) applications. All channels can be operated in the same mode, or channels may be individually wired for operation in either current loop output or voltage output applications. The outputs from 50-pin edge connector J1 on the Multimodule board are pin-compatible with the iCS 910 Signal Conditioning/Termination Panel.

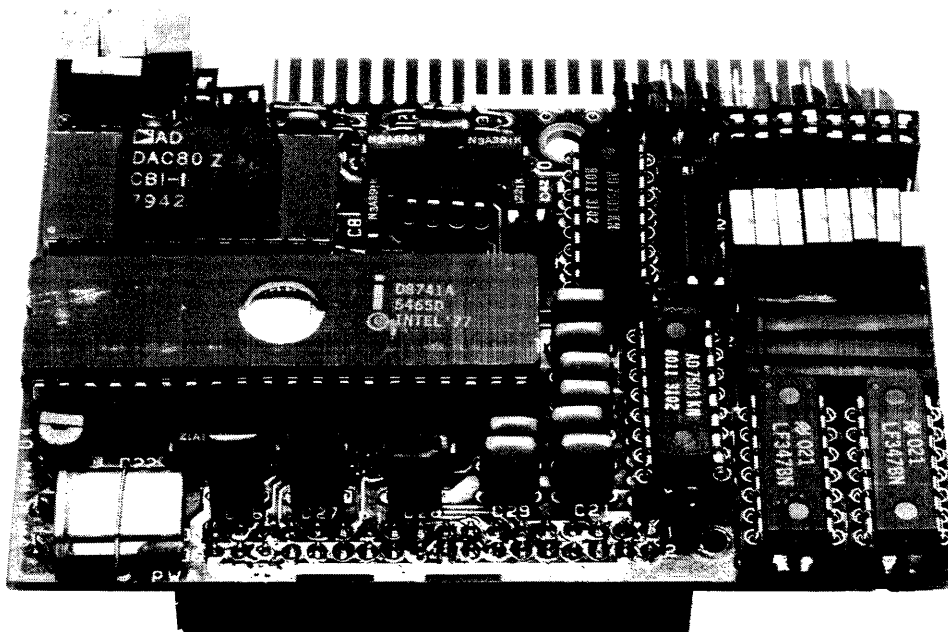


Figure 1-1. iSBX™ 328 Analog Output Multimodule™ Board

## GENERAL INFORMATION

All data to be output through the Multimodule board is transferred from the host iSBC microcomputer to the Multimodule board via the iSBX bus connector (P1). The UPI device on the Multimodule board accepts the binary digital data and generates a 12-bit data word for the Digital-to-Analog Converter (DAC) and a four bit channel decode/enable for selecting the output channel. The DAC transforms the data into analog signal outputs for either voltage output mode or current loop output mode. Offsetting of the DAC voltage in current output mode may be performed by the UPI software offset routine or by the hardware offset adjustments included on the board. The Multimodule board status is available via the iSBX bus connector (P1).

### 1-3. EQUIPMENT SUPPLIED

The Multimodule board plugs directly onto the host iSBX microcomputer, thereby requiring no cable interface. The following equipment is supplied with the iSBX 328 Analog Output Multimodule Board:

- a. Schematic Diagram, drawing number 142760.
- b. Two plastic mounting screws, 1/4 6-32.
- c. One plastic mounting spacer, 1/2 6-32.

### 1-4. COMPATIBLE EQUIPMENT

The Multimodule board must be used with a host iSBC microcomputer that contains an iSBX bus connector. Multibus interfacing is performed indirectly through the host iSBC microcomputer.

The output connector (J1) on the Multimodule board interfaces readily to an iCS 910 Analog Signal Conditioning/Termination Panel through the J2 connector on the panel. Although the outputs are not pin-for-pin compatible, the Multimodule board can be installed into most analog output applications satisfied by an iSBC 724 or 732 board.

### 1-5. SPECIFICATIONS

The specifications for the iSBX 328 Analog Output Multimodule Board are listed in Table 1-1.

GENERAL INFORMATION

Table 1-1. Specifications

<p><b>POWER REQUIREMENTS</b>  Vcc u +5 volts (+0.25 volts)  Vdd u +12 volts (+0.6 volts)   Vss = -12 volts (+0.6 volts)</p>	<p>Icc = 140 mA maximum  Idd = 45 mA (Voltage Mode)  Idd = 200 mA (Current Loop Mode, if iSBX 328 Vdd is used).  Iss = 60 mA maximum</p>
<p><b>PHYSICAL CHARACTERISTICS</b>  Height:   Width:  Length:  Weight:</p>	<p>2.03 cm (0.80 inch) Multimodule board.  2.82 cm (1.13 inch) Multimodule and iSBC boards.  6.36 cm (2.50 inches)  9.40 cm (3.70 inches)  85 gm (2.98 ounces)</p>
<p><b>ENVIRONMENTAL REQUIREMENTS</b>  Operating Temperature:  Relative Humidity:</p>	<p>0° to 55°C (32° to 131°F)  To 90% (without condensation)</p>
<p><b>INTERFACE COMPATIBILITY</b>  Connector P1:   Connector J1:</p>	<p>Compatible with the iSBX bus interface requirements.  Analog pin-out compatible with the ICS 910 Analog Signal Conditioning/Termination Panel and similar to the iSBC 724 and 732 boards. Connector details are listed in Chapter 2.</p>
<p><b>OPERATING CHARACTERISTICS</b>  Outputs:   Voltage Ranges:   Current Loop Range:   Output Current:   DAC Resolution:   DAC Slew Rate:</p>	<p>8 channels, each idependently jumpered for voltage output or current loop output mode.   0 to +5 volts (unipolar operation).  -5 to +5 volts (bipolar operation).   4 to 20 mA.   +5 mA maximum (voltage mode-bipolar operation).   12 bits.   0.01 volt per microsecond minimum.</p>

GENERAL INFORMATION

Table 1-1. Specifications (continued)

DAC Accuracy (%FSR / C):

Mode	Accuracy	Ambient Temp
Voltage-Unipolar, typical	+0.025% FSR	@ 25°C
Voltage-Unipolar, maximum	+0.035% FSR	@ 25°C
Voltage-Unipolar, typical	+0.08% FSR	@ 0° to 60°C*
Voltage-Unipolar, maximum	+0.17% FSR	@ 0° to 60°C*
Voltage-Bipolar, typical	+0.025% FSR	@ 25°C
Voltage-Bipolar, maximum	+0.035% FSR	@ 25°C
Voltage-Bipolar, typical	+0.09% FSR	@ 0° to 60°C*
Voltage-Bipolar, maximum	+0.17% FSR	@ 0° to 60°C*
Current Loop, typical	+0.07% FSR	@ 25°C
Current Loop, maximum	+0.08% FSR	@ 25°C
Current Loop, typical	+0.17% FSR	@ 0° to 60°C
Current Loop, maximum	+0.37% FSR	@ 0° to 60°C

\*(At = 35°C)

Temperature Coefficient:

Mode	Gain TC	Offset TC
Voltage-Unipolar, typical	16 ppm	06 ppm
Voltage-Unipolar, maximum	33 ppm	17 ppm
Voltage-Bipolar, typical	16 ppm	08 ppm
Voltage-Bipolar, maximum	33 ppm	15 ppm
Current Loop, typical	43 ppm	07 ppm
Current Loop, maximum	87 ppm	18 ppm

GENERAL INFORMATION

Table 1-1. Specification (continued)

REFRESH AND THROUGHPUT RATES**	
Refresh 1 channel (no new data):	80 us
Refresh all 8 channels (no new data):	650 us
Update and refresh 1 channel with new data firmware program 2	150 us
for each additional channel	130 us
Update and refresh 1 channel with new data firmware program 1 or 3	200 us
for each additional channel	155 us
Update and refresh all 8 channels (all new data): firmware program 2	1.050ms
per channel of new data	50 us
Update and refresh all 8 channels (all new data): firmware program 1 or 3	1.280 ms
per channel of new data	80 us
** All times nominal	

## CHAPTER 2. PREPARATION FOR USE

### 2-1. INTRODUCTION

This chapter of the text provides information on preparing and installing the iSBX 328 Analog Output Multimodule Board. The information presented in this chapter includes the following:

- unpacking and inspection instructions
- dc characteristics
- connector assignments
- jumper configurations
- installation considerations such as physical, power, cooling, and mounting requirements
- installation procedures

### 2-2. UNPACKING AND INSPECTION

Prior to opening the shipping carton, inspect the carton containing the iSBX 328 board for evidence of mishandling during shipment.

If the shipping carton shows evidence of shipping damage or is waterstained, request that the carrier's agent be present when the carton is opened. If the carrier's agent is not present when a damaged carton is opened, save the carton and all packing materials for the agent's later inspection. The carrier's agent may also request photos of the equipment as it was unpacked. Inspect each component as it is removed from the shipping carton and note any evidence of physical damage.

If the shipping carton is not visibly damaged, carefully unpack the iSBX 328 board and inspect it for any evidence of physical damage. If any concealed shipping damage is found, contact the carrier's agent for further instructions.

Refer to Chapter 5, Service Information, for instructions on how to obtain repair for a iSBX 328 board damaged in shipment. A purchase order is required for all repairs resulting from shipping damage. The purchase order is your proof of loss and a copy should be submitted along with your claim to the carrier.

The salvageable shipping cartons and packing material can be saved for future use in the event that shipment of the iSBX 328 board is required.

### 2-3. INSTALLATION CONSIDERATIONS

Installation considerations such as power, cooling, mounting, and physical size requirements, are outlined in the following paragraphs.

## PREPARATION FOR USE

### 2-4. POWER REQUIREMENTS

The Multimodule board requires three voltages for operations; +5 volts (+0.25 volt) at 140 mA maximum, -12 volts (+0.6 volt) at 60 mA maximum and +12 volts (+0.6 volt) at 45 mA maximum (200 mA maximum current for a current loop application when the iSBX 328 board power is used). All power for the Multimodule board is drawn through the iSBX bus connector (P1) on the board.

The Multimodule board uses the -12 volt power provided through the iSBX bus connector and components R7 and VR1 to create a -6.4 volt reference for use with the analog circuitry. A reference voltage of +6.3 volts is generated within the DAC.

### 2-5. COOLING REQUIREMENTS

The Multimodule board dissipates 27.9 gramcalories/minute (0.11 BTU/minute) of heat and adequate circulation of air must be provided to prevent a temperature rise above 55°C (134°F).

### 2-6. PHYSICAL DIMENSIONS

The outside dimensions of the Multimodule board are as follows:

- a. Width: 6.35 cm (2.50 inches).
- b. Length: 9.40 cm (3.70 inches).
- c. Height: 1.40 cm (0.56 inch) Multimodule board only.  
2.82 cm (1.13 inches) Multimodule and iSBC boards.

The iSBX 328 board is a single width multimodule and can be installed on any iSBC board that implements the iSBX bus. Figure 2-1 shows the board outline, and the connector and jumper locations for the iSBX 328 board.



PREPARATION FOR USE

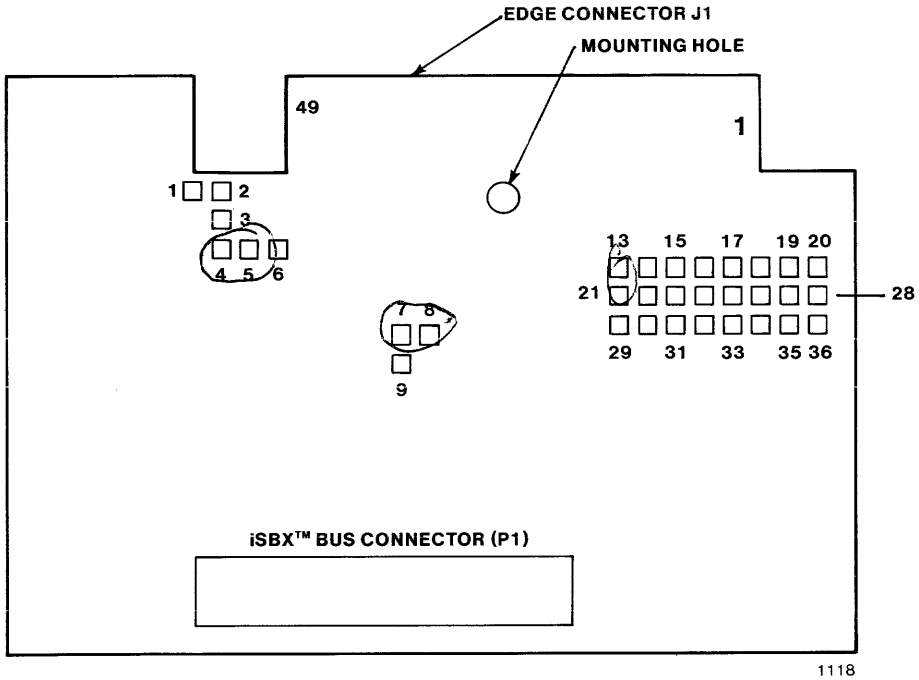


Figure 2-1. Board Outline And Jumper Locations

2-7. DC INTERFACE CHARACTERISTICS

The dc characteristics of the iSBX 328 Analog Output Multimodule Board at the P1 connector are listed in Table 2-1.

Table 2-1. DC Interface Characteristics

Output Signal	Type Driver	I <sub>OL</sub> MAX (mA)	V <sub>OL</sub> MAX (I <sub>OL</sub> =MAX)	I <sub>OH</sub> MIN (uA)	V <sub>OH</sub> MIN (I <sub>OH</sub> =MIN)	C <sub>O</sub> MIN (pf)
MDO-MD7	TRI	2.0	0.45	-400	2.4	130
Input Signal	Type Receiver	I <sub>IL</sub> MIN (F <sub>IL</sub> =0.4)	V <sub>IL</sub> MAX	I <sub>IH</sub> MAX (V <sub>IH</sub> =2.4)	V <sub>IH</sub> MAS	C <sub>I</sub> MAX (pf)
MDO-MD7	TRI	-0.01	0.8	10	2.0	12
MAO	TTL	-0.01	0.8	10	2.0	10
MCSO/	TTL	-0.01	0.8	10	2.0	10
MRESET	descrete	-1.5	0.4	1	5.0*	10
IOWRT/, IORD/	TTL	-0.01	0.8	10	2.0	10

TTL = Standard Totem Pole Output  
 TRI = Three-State Output  
 \*Indicates that a pull-up resistor is required for the transistor.

2-8. JUMPER CONFIGURATIONS

The iSBX 328 Analog Output Multimodule Board provides 33 jumper posts to configure the functions as outlined in Table 2-2 and detailed in the following paragraphs. Table 2-3 lists the board configuration specifications and notes the factory shipped configuration of the board. Figures 2-2 through 2-6 illustrate the active circuit for each board configuration.

Multiplexer Select. Three additional jumper pads, E10, E11, and E12 configure the board for the type of multiplexer installed onto the board at chip locations U3 and U5. The jumper is factory configured for the multiplexer installed and must not be modified. Refer to the replaceable parts list in Chapter 5 for additional information.

PREPARATION FOR USE

Table 2-2. User-Configurable Jumpers

Jumper Numbers	Functions	Comments
E1,E2	Hardware Configured	Connection of E1 to E2 allows on-board control of the offset current generation (up to 4 mA for a 4 to 20 mA current loop).
E7,E8, E9	Mode Selection	Connect <u>E7 to E8</u> for voltage output operation. Connect E7 to E9 for hardware current loop output operation.
E3,E4, E5,E6	DAC Mode Selection	Connect E3 to E4 and E5 to E6 for unipolar voltage (0 to +5 volts) and hardware current loop output operation. Connect <u>E4 to E5</u> for bipolar voltage output operation ( <u>+5 volts</u> ).
E13,E21, E29	Channel 7 Output	Connect E13 to E21 to use Channel 7 in voltage output mode. Remove E13 to E21 and install E21 to E29 to use Channel 7 in current loop output mode.
E14,E22, E30	Channel 6 Output	Connect E14 to E22 to use Channel 6 in voltage output mode. Remove E14 to E22 and install E22 to E30 to use Channel 6 in current loop output mode.
E15,E23, E31	Channel 5 Output	Connect E15 to E23 to use Channel 5 in voltage output mode. Remove E15 to E23 and install E23 to E31 to use Channel 5 in current loop output mode.
E16,E24, E32	Channel 4 Output	Connect E16 to E24 to use Channel 4 in voltage output mode. Remove E16 to E24 and install E24 to E32 to use Channel 4 in current loop output mode.
E17,E25, E33	Channel 3 Output	Connect E17 to E25 to use Channel 3 in voltage output mode. Remove E17 to E25 and install E25 to E33 to use Channel 3 in current loop output mode.
E18,E26, E34	Channel 2 Output	Connect E18 to E26 to use Channel 2 in voltage output mode. Remove E18 to E26 and install E26 to E34 to use Channel 2 in current loop output mode.
E19,E27, E35	Channel 1 Output	Connect E19 to E27 to use Channel 1 in voltage output mode. Remove E19 to E27 and install E27 to E35 to use Channel 1 in current loop output mode.
E20,E28, E36	Channel 0 Output	Connect <u>E20 to E28</u> to use Channel 0 in voltage output mode. Remove E20 to E28 and install E28 to E36 to use Channel 0 in current loop output mode.

PREPARATION FOR USE

Table 2-3. Board Configuration Specifications

JUMPER POSITION	CONFIGURATION A	CONFIGURATION B	CONFIGURATION C	CONFIGURATION D	CONFIGURATION E
E1 TO E2	OUT	OUT	IN	OUT	OUT
E3 TO E4	IN	IN	IN	OUT	OUT
E5 TO E6	IN	IN	IN	OUT	OUT
E4 TO E5	OUT	OUT	OUT	IN	IN
E7 TO E8	IN	IN	OUT	IN	IN
E7 TO E9	OUT	OUT	IN	OUT	OUT
E13 TO E21	IN	AS REQUIRED	OUT	IN	AS REQUIRED
E21 TO E29	OUT	AS REQUIRED	IN	OUT	AS REQUIRED
E14 TO E22	IN	AS REQUIRED	OUT	IN	AS REQUIRED
E22 TO E30	OUT	AS REQUIRED	IN	OUT	AS REQUIRED
E15 TO E23	IN	AS REQUIRED	OUT	IN	AS REQUIRED
E23 TO E31	OUT	AS REQUIRED	IN	OUT	AS REQUIRED
E16 TO E24	IN	AS REQUIRED	OUT	IN	AS REQUIRED
E24 TO E32	OUT	AS REQUIRED	IN	OUT	AS REQUIRED
E17 TO E25	IN	AS REQUIRED	OUT	IN	AS REQUIRED
E25 TO E33	OUT	AS REQUIRED	IN	OUT	AS REQUIRED
E18 TO E26	IN	AS REQUIRED	OUT	IN	AS REQUIRED
E26 TO E34	OUT	AS REQUIRED	IN	OUT	AS REQUIRED
E19 TO E27	IN	AS REQUIRED	OUT	IN	AS REQUIRED
E27 TO E35	OUT	AS REQUIRED	IN	OUT	AS REQUIRED
E20 TO E28	IN	AS REQUIRED	OUT	IN	AS REQUIRED
E28 TO E36	OUT	AS REQUIRED	IN	OUT	AS REQUIRED

Configuration A - Unipolar, voltage only output

Configuration B - Unipolar, voltage or current loop output, software provided offset/gain.

Configuration C - Unipolar, current loop only, hardware provided offset/gain. Must have all outputs configured for current loop operation.

Configuration D - Bipolar, voltage only output. Standard factory configuration.

Configuration E - Bipolar, voltage or current loop output, software provided offset/gain.

PREPARATION FOR USE

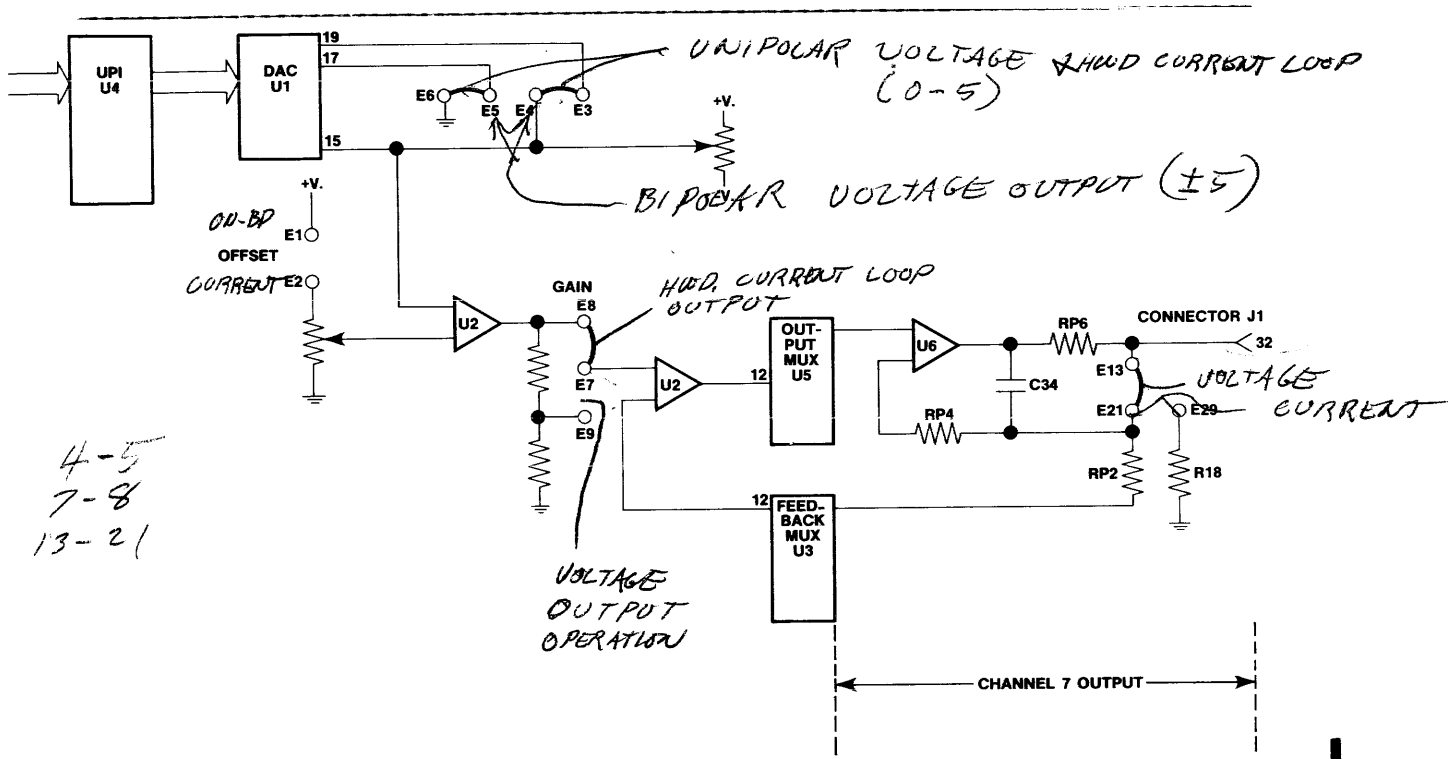


Figure 2-2. Configuration A--Unipolar Voltage Only, Output

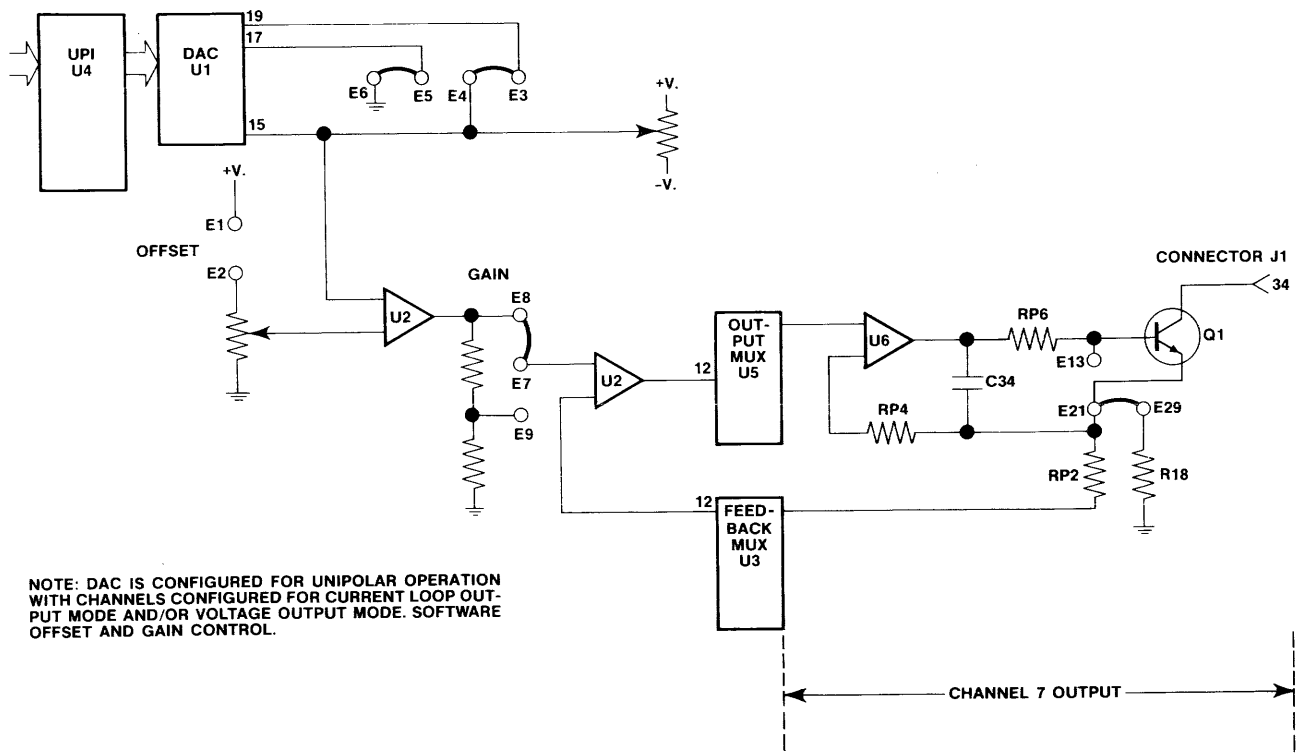


Figure 2-3. Configuration B--Mixed Unipolar Output (Current Loop Shown), Software Offset/Gain

PREPARATION FOR USE

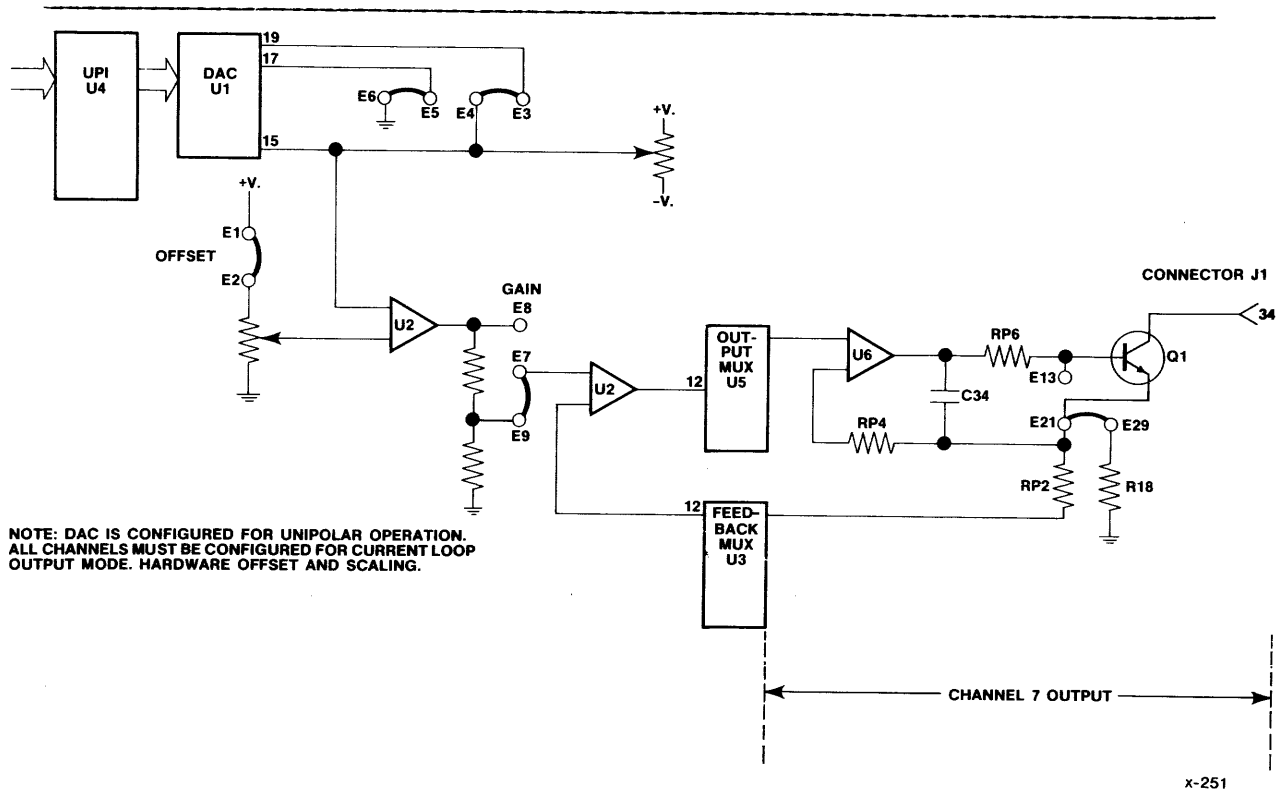


Figure 2-4. Configuration C--Current Loop Only, Hardware Offset/Gain

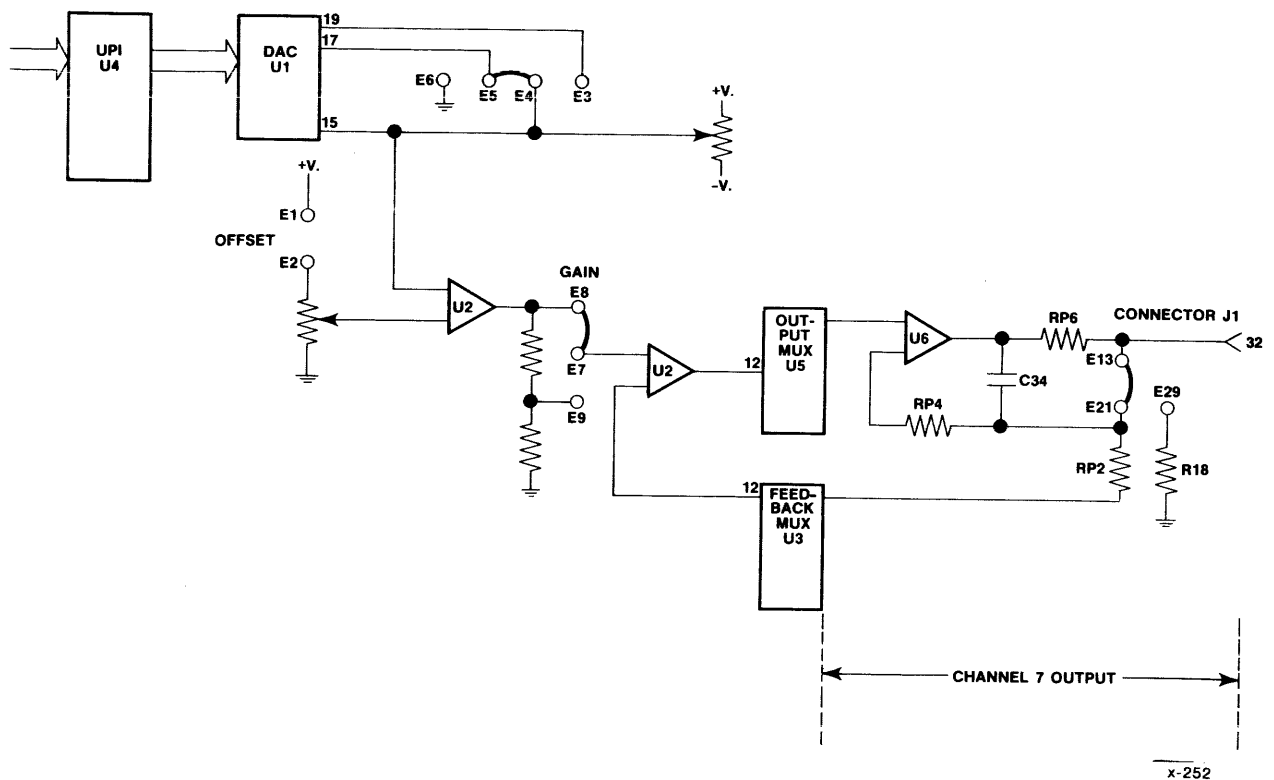


Figure 2-5. Configuration D--Bipolar, Voltage Only, Output

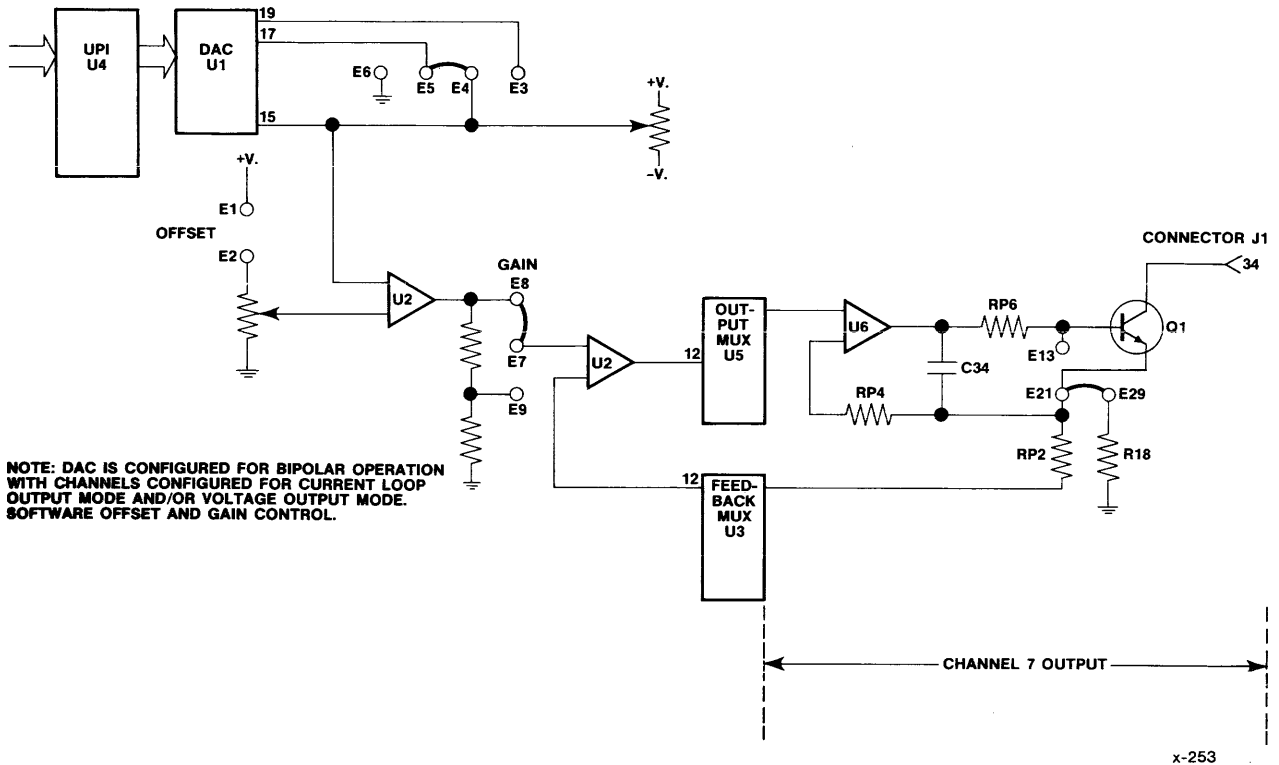


Figure 2-6. Configuration E--Mixed Bipolar Output (Current Loop Shown), Software Offset/Gain

## PREPARATION FOR USE

Hardware Current Loop Offset Generation. Jumpers E1 to E2 and E7 to E9 are used only in a current loop output mode where an on-board hardware generated offset must be provided to amplifier U2. When E1 is connected to E2, the 4 mA offset current is user-adjustable via variable resistor R3. The jumper is not required if operating in a voltage output mode or if generating offset via software. The jumper connecting E7 to E9 serves to scale the DAC voltage plus any offset voltage for a 4 to 20 mA current range.

### NOTE

Current offset may be generated by the software of the host iSBC microcomputer before the data is transferred to the Multimodule board or by the firmware located within the 8041 UPI device on the Multimodule board.

DAC Mode Configuration. Jumpers E3 to E4 control the amount of feedback resistance inserted into the feedback loop between the DAC and amplifier U2 on the Multimodule board, and selects, along with E5 to E6, the DAC voltage output range. With E3 to E4 and E5 to E6 connected, the board is configured for unipolar voltage output mode operation with the analog output from the DAC in the range of 0 to +5 volts. Ground is provided to pin 17 of the DAC to maintain a constant current flow through the DAC.

Removing the jumpers connecting E3 to E4 and E5 to E6 and installing a jumper connecting E4 to E5 provides a half scale offset and selects the bipolar voltage configuration for the Multimodule board. In bipolar voltage output mode, the DAC analog output range is from -5 to +5 volts.

Channel Output Mode. The type of signal output from the buffer amplifiers (U6 and U7) is jumper selectable via three jumper posts at the output of each channel. These jumper posts allow the user to configure the output of each channel to either current loop output mode or voltage output mode. Table 2-2 lists the jumpers for each channel and their functions.

As an example, when E20 is jumpered to E28, channel 0 operates in the voltage output mode. In this mode, the buffer amplifier performs as a unity gain storage register for the DAC channel output voltage. When jumper posts E20 and E28 are disconnected and E28 and E36 are connected together, channel 0 operates in a current loop output mode. In this mode, the buffer amplifier functions as a 4 to 20 mA current converter, buffering the sample-and-hold capacitors and maintaining a constant voltage across the sampling resistors (R18 through R25).



PREPARATION FOR USE

2-9. CONNECTOR CONFIGURATION

The Multimodule board contains two connectors, the iSBX bus connector (P1) and the 50-pin edge connector (J1). Each of these is described in the following paragraphs.

The iSBX bus connector (P1) interfaces the Multimodule board to any host iSBC microcomputer that contains an iSBX bus connector. The subset of iSBX signals implemented in the iSBX 328 is listed in Table 2-4 and described in Chapter 4.

Table 2-4. iSBX™ BUS Pin Assignment

Pin	Mnemonic	Description	Pin	Mnemonic	Description
35	GND	SIGNAL GROUND	36	+5	+5V
33	MD0	MDATA BIT 0	34		Reserved
31	MD1	MDATA BIT 1	32		Reserved
29	MD2	MDATA BIT 2	30		Reserved
27	MD3	MDATA BIT 3	28		Reserved
25	MD4	MDATA BIT 4	26		Reserved
23	MD5	MDATA BIT 5	24		Reserved
21	MD6	MDATA BIT 6	22	MSCO/	M CHIP SELECT 0
19	MD7	MDATA BIT 7	20		Reserved
17	GND	SIGNAL GROUND	18	+5V	+5V
15	IORD/	IO READ COMMAND	16		Reserved
13	IOWRT/	IO WRITE COMMAND	14		Reserved
11	MA0	M ADDRESS 0	12		Reserved
9		Reserved	10		Reserved
7		Reserved	8	MPRT	M PRESENT
5	RESET	RESET	6		Reserved
3	GND	SIGNAL GROUND	4	+5V	+5V
1	+12V	+12V	2	-12V	-12V

Connector J1 interfaces the Multimodule board to the application via user-supplied data lines (channels). The channel output found on each pin of connector J1 is listed in Table 2-5. Table 2-6 contains a listing of the details for the user-supplied, mating, 50-pin (0.1 pin centers) receptacles used interface the J1 connector on the Multimodule board to the user application.

For voltage only operation or for current loop operation with software provided offset/gain, a separate wire should be provided for each analog return listed under voltage output mode on Table 2-5. Use of the external supply returns (pins 47 and 48), is optional unless connection is made to either the +12 vdc or -12 vdc pins.

PREPARATION FOR USE

Table 2-5. Connector J1 Pin Assignment

Pin	Voltage Output Mode	Current Loop Output Mode	Pin	Voltage Output Mode	Current Loop Output Mode
1	Not Used	Not Used	2	Not Used	Not Used
3	Analog Return	Not Used	4	Channel 0 data	Not Used
5	Analog Return	Not Used	6	Not Used	Channel 0 data
7	Analog Return	Not Used	8	Channel 1 data	Not Used
9	Analog Return	Not Used	10	Not Used	Channel 1 data
11	Analog Return	Not Used	12	Channel 2 data	Not Used
13	Analog Return	Not Used	14	Not Used	Channel 2 data
15	Analog Return	Not Used	16	Channel 3 data	Not Used
17	Analog Return	Not Used	18	Not Used	Channel 3 data
19	Analog Return	Not Used	20	Channel 4 data	Not Used
21	Analog Return	Not Used	22	Not Used	Channel 4 data
23	Analog Return	Not Used	24	Channel 5 data	Not Used
25	Analog Return	Not Used	26	Not Used	Channel 5 data
27	Analog Return	Not Used	28	Channel 6 data	Not Used
29	Analog Return	Not Used	30	Not Used	Channel 6 data
31	Analog Return	Not Used	32	Channel 7 data	Not Used
33	Analog Return	Not Used	34	Not Used	Channel 7 data
35	Not Used	Not Used	36	Not Used	Not used
37	Not Used	Not Used	38	Not Used	Not used
39	Not Used	Not Used	40	Not Used	Not used
41	Not Used	Not Used	42	Not Used	Not used
43	Not Used	Not Used	44	Not Used	Not used
45	Not Used	Not Used	46	Not Used	Not used
47	Not Used	Ext. Supply Return	48	Not Used	Ext. Supply Return
49	-12V	-12V	50	+12V	+12V

Note: All odd-numbered pins (1, 3,...49) are on component side of the board. Pin 1 is the right-most pin when J1 is viewed from the component side with J1 at the top.

PREPARATION FOR USE

Table 2-6. Mating J1 Receptacles

Receptacle Type	Vendor	Part No.
Female, Flat Crimp	3M AMP ANSLEY SAE	3415-0001 W/O EARS 88083-1 609-5015 SD6750 SERIES
Female, Soldered	AMP VIKING TI	2-583485-6 3KH25/9JN5 H312125
Female, Wirewrap	TI VIKING ITT	H421011-25 3KH25/JND5 EC4A050A1A

For current loop only operation (hardware provided offset/gain) the external supply returns (pins 47 and 48) also function as the current loop ground reference and must be connected to the receiving device. If multiple receiving devices are used, a separate return line must be connected to each device.

2-10. BOARD INSTALLATION

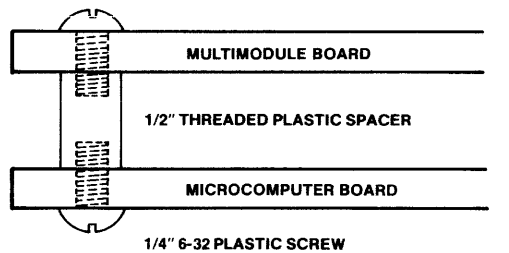
The Multimodule board mounts directly onto a host iSBC microcomputer by means of an iSBX bus connector. Depending on the chassis or card cage used, installation of multimodule on the iSBC board may require leaving the card slot adjacent to the component side of the iSBC board empty. Figure 2-7 shows the assembly of the mounting screws and spacer. Install the board onto a host iSBC microcomputer as follows.



Remove power from the system before inserting or removing iSBC micro-computer boards into/from a cardcage. Failure to do so could result in damage to the boards.

PREPARATION FOR USE

1. With a plastic screw, 1/4 by 6-32, secure the plastic 1/2 by 6-32 spacer to the host iSBC board.
2. Locate pin 1 of the iSBX bus connector (P1) on the Multimodule board and align it with pin 1 of the iSBX bus connector on the host iSBC microcomputer.
3. Align the mounting hole on the Multimodule board with the mounting spacer installed onto the host iSBC board in Step 1.
4. Gently press the two boards together until the connector sets.
5. Secure the Multimodule board to the top of the spacer with another plastic 1/4 by 6-32 screw.



x-254

Figure 2-7. Mounting Technique

---

NOTE

The location of an installed Multimodule board and the iSBX bus connector number of the host iSBC microcomputer may vary according to the type of host iSBC microcomputer that is used.

## CHAPTER 3. PROGRAMMING INFORMATION

### 3-1. INTRODUCTION

This chapter describes the programming of the iSBX 328 Analog Output Multimodule Board. Included are sections on addressing, programming requirements, interrupt servicing, and programming examples. More information on programming of the 8401 UPI device is contained in the INTEL UPI-41 USER'S MANUAL. Appendix A at the end of the manual is a sample program for use in calibrating the iSBX 328 board.

### 3-2. ADDRESSING

The host iSBC microcomputer addresses the Multimodule board by executing an IN or OUT instruction specifying the port address for the iSBX connector where the iSBX 328 is mounted. Table 3-1 lists all of the legal port addresses for Multimodule boards. Because the host iSBC microcomputers may accept more than one Multimodule board, the upper address byte for each iSBX bus connector is variable and shown in Table 3-1 as an X.

Table 3-1. I/O Port Addresses

Function	8-Bit Port Address	6-Bit Port Address	Comments
READ STATUS	X1,X3,X5, or X7	X2,X6,XA, or XE	READ contents of status register from UPI.
WRITE DATA	X0,X2,X4, or X6	X0,X4,X8, or XC	WRITE data, initialization word, low byte, or high byte to UPI.
WRITE RESET	X1,X3,X5, or X7	X2,X6,XA, or XE	WRITE any data pattern to the Multimodule board to reset UPI.

### 3-3. PROGRAMMING SEQUENCE

The programming sequence required by the board is relatively straight-forward. In order to output converted data onto one of the channels, the user first must configure the Multimodule board jumpers to allow operation suitable for the application and then perform the following operations in the sequence listed. Each operation is detailed further in subsequent paragraphs of the text.

## PROGRAMMING INFORMATION

1. Check the status from the Multimodule board to ensure that the board is ready to accept an initialization byte from the host iSBC microcomputer board. Status bit 3 (FO) is HIGH when the UPI is ready to accept the initialization byte.
2. Initialize the UPI device for proper operation during the data output sequence. This includes selecting the number of channels to be scanned and selecting one of the 3 resident programs within the UPI to be run.
3. Transfer the LOW BYTE of the data to the selected channel. This entails placing the digital data from the host iSBC microcomputer into the UPI device and allowing the firmware to decode and save it until the HIGH BYTE is received.
4. Check the status of the Multimodule board on completion of the operation. This consists of user programming that allows the host iSBC microcomputer board to read the status byte from the Multimodule board on completion of the data conversion and transfer sequence. The next byte of data cannot be transferred to the UPI device until the input buffer is not full (IBF=0).
5. Transfer the HIGH BYTE of data to the selected channel. This entails placing the digital data from the host iSBC microcomputer into the UPI device and allowing the firmware to combine it with the LOW BYTE (previously converted) and send it to the proper channel address.
6. Check the status of the Multimodule board on completion of the operation. This consists of reading the status byte from the Multimodule board on completion of the data conversion and transfer sequence and checking for IBF=0.

### 3-4. UPI INITIALIZATION SEQUENCE

To begin a data transfer operation, the user must, through programming, initialize the UPI device before the Multimodule board can begin accepting output data from the host iSBC microcomputer. The process of initializing the board for an output operation (after a power-on RESET or a software RESET) is performed by issuing an initialization byte to the UPI. The initialization byte for the UPI selects the firmware program that the UPI will perform (whether program 1, 2, 3, or 4) and the address of the last channel to be services (from 1 to 8). Figure 3-1 shows the format of the initialization byte required by the UPI and includes both the mode and last channel address fields.

Mode Select. Bits 3 and 4 of the initialization byte (refer to Figure 3-1) select which type of configuration and offset generation is to be used during the operation by allowing one of four firmware programs within the UPI to be run. The UPI firmware uses bits 3 and 4 to determine what type of current offset generation it is working with and what mode of operation the channel is operating in (whether current loop output mode or voltage output mode).

PROGRAMMING INFORMATION

When bits 3 and 4 are zero, firmware program 1 is selected. Program 1 assumes the on-board DAC is configured for unipolar operation and the channel configurations are mixed; i.e., some channels are configured for operation in the voltage output mode and some in the current loop output mode. This routine does not attempt to alter the data destined for a voltage output channel, however, data for a current loop output channel is scaled and offset.

When bit 4 is a 0 and bit 3 is a 1, firmware program 2 is selected. Program 2 assumes the board is configured for either unipolar or bipolar operation and all channels are configured for operation in the voltage or hardware current loop output mode. This program within the firmware does not offset or scale the data output from the UPI.

When bit 4 is a 1 and bit 3 is a 0, firmware program 3 is selected. Program 3 assumes the on-board DAC is configured to operate as bipolar and the channel configurations are mixed; i.e., some channels are configured for operation in the voltage output mode and some for the current loop output mode. This program does not attempt to alter the data destined for a voltage output channel, however, data for a current loop output channel is scaled and offset.

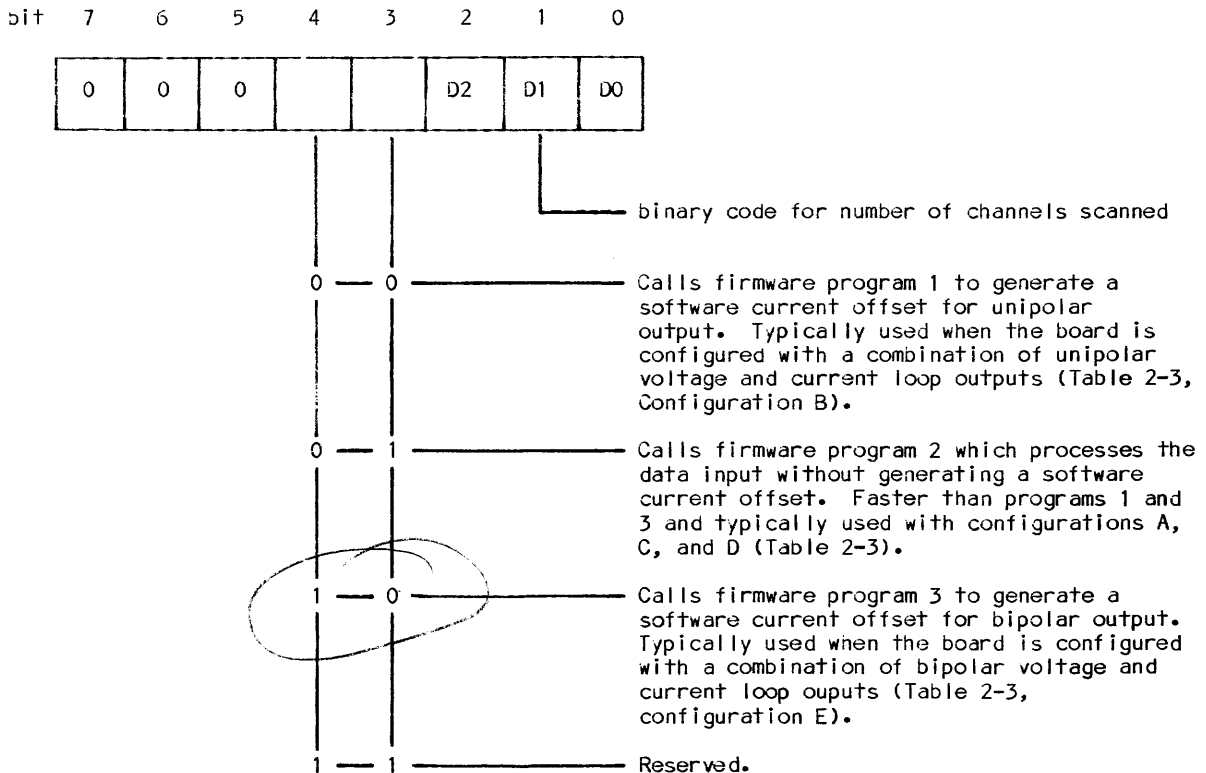


Figure 3-1. Initialization Byte Format

## PROGRAMMING INFORMATION

Channel Address Select. Bits 2 through 1 of the initialization byte provide the user with a means of selecting how many of the 8 channels are scanned. The firmware decodes bits 0, 1, and 2 as a binary count and scans a channel for each count, starting with channel 0. Any number of channels from one to eight may be selected and scanned, however, the channels selected to be scanned must be consecutive addresses starting from address 0. The channel scanning speed is inversely proportional to the number of channels selected; i.e., a four-times greater scanning speed can be attained with a one-channel scan than with a four-channel scan. In general, a faster scan rate can be attained by executing program 2 within the firmware; the UPI does not perform as many operations on the data. The remaining 3 bits of the initialization byte are reserved and should be set to zero.

### 3-5. DATA TRANSFER SEQUENCE

Data is transferred from the host iSBC microcomputer to the Multimodule board in a two byte format as depicted by the HIGH ORDER BYTE and the LOW ORDER BYTE in Figure 3-2. Each output to the Multimodule board must include two bytes of data. The UPI firmware on the Multimodule board requires that the LOW ORDER BYTE be received first so that the board can begin decoding the DAC channel address as early as possible. The functions performed by each of the data bytes is described in the following paragraphs.

When the HIGH ORDER BYTE is loaded into the input buffer in the UPI device, it contains the upper 8 bits (bits D11 through D4) of the 12-bit data word that is to be converted to an analog output.

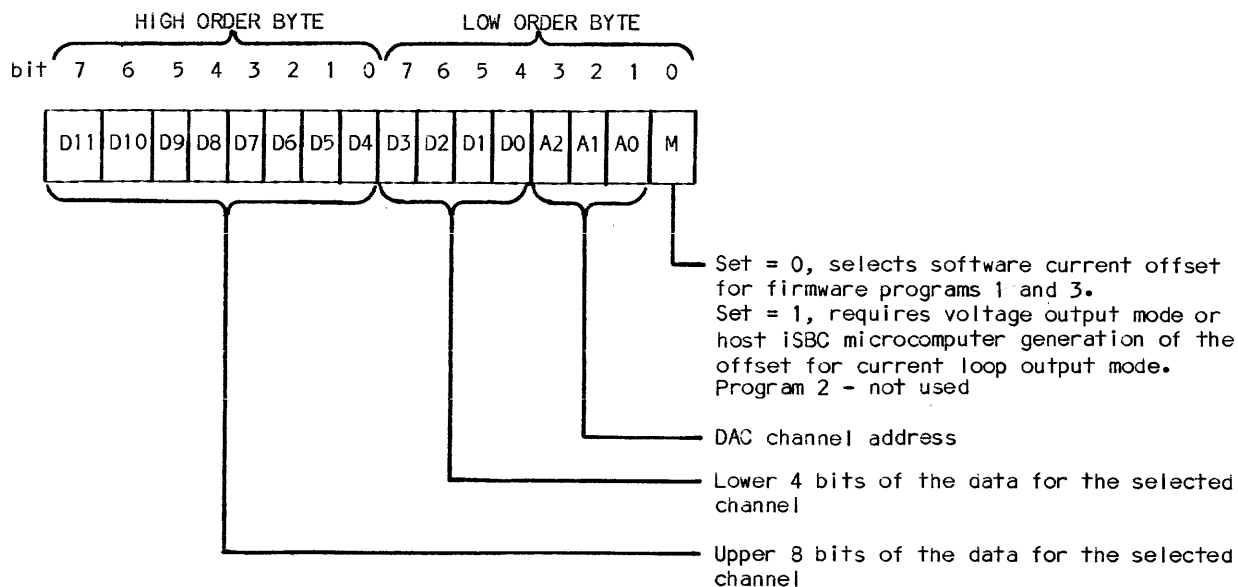
The LOW ORDER BYTE includes the lower 4 bits (bits D3 through D0) of the data word, the 3-bit address of the DAC channel (bits A3, A2, and A1) to which the data is sent, and the mode indicator bit (M). The condition of the mode indicator bit (M) must comply with the mode of operation selected in the initialization byte. The M bit, bit 0 of the LOW ORDER BYTE, selects the operating mode for that channel of the Multimodule board addressed by bits 1 through 3 of the LOW ORDER BYTE. When set to 0, the M bit indicates to the firmware that the channel is to operate in the current loop output mode with the 8041 UPI generating the current offset and gain. When set to 1, the M bit indicates to the firmware the channel is to operate in either the voltage output mode or the current loop output mode with any required current offset generated on the host iSBC microcomputer. If program 2 is selected, the state of bit 0 of the LOW ORDER BYTE is not checked by the UPI firmware.

### 3-6. STATUS CHECKING SEQUENCE

The Multimodule board includes a status byte as shown in Figure 3-3. The status byte for the Multimodule board is read into the host iSBC microcomputer by issuing an IN command specifying one of the legal status port addresses for the Multimodule board.



PROGRAMMING INFORMATION



VOLTAGE OUTPUT REFERENCE

SCALE	D11-D0	UNIPOLAR VOLTAGE	BIPOLAR VOLTAGE
MINIMUM	000H	0.0V	-5.0V
HALF	800H	+2.5V	0.0V
FULL	FFFH	+4.9988V	+4.9975V

SCALING - Unipolar, 1.22 mV/Bit; Bipolar, 2.44 mV/bit

Figure 3-2. Data Word Format

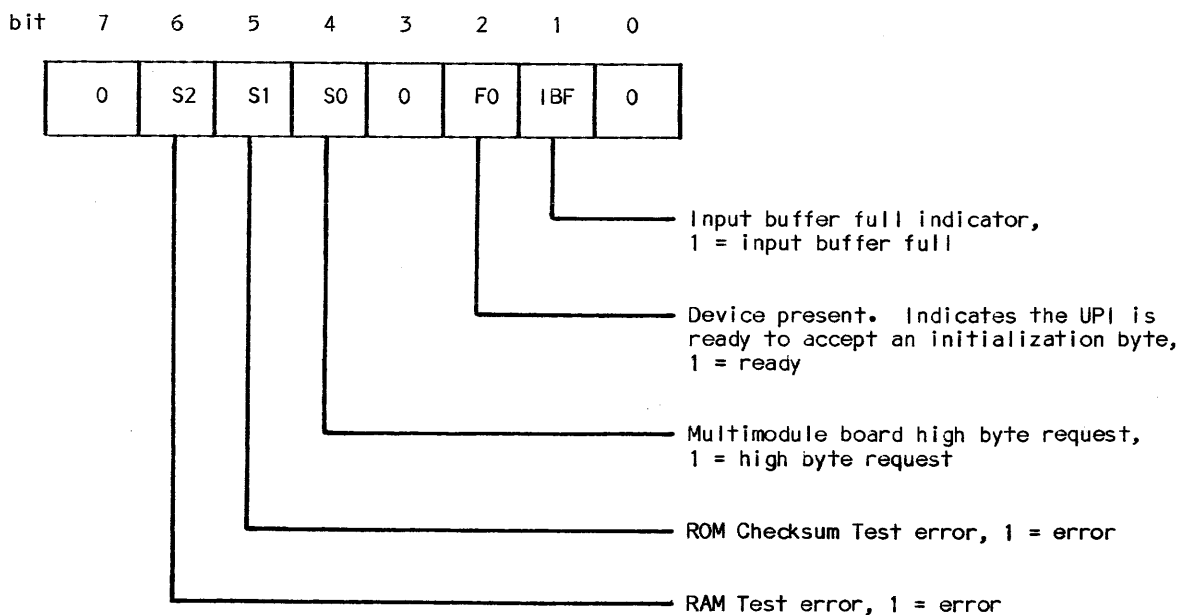


Figure 3-3. Status Byte Format

## PROGRAMMING INFORMATION

The input buffer full indicator, bit 1 of the status byte, indicates the condition of the input buffer within the UPI on the Multimodule board and should be checked before every data transfer from the host to the Multimodule board, including a check before initialization byte transfer. When data is transferred from the host iSBC microcomputer to the input buffer in the UPI device, it sets bit 1 of the status byte to 1 indicating the input buffer is full. The UPI sets the IBF flag in the status byte to 0 when it reads and begins processing the data from the input buffer.

The Ready-For-Initialization Byte indicator (FO), bit 2 of the status byte, indicates when the UPI is ready to accept the initialization byte. The UPI sets bit 2 to 1 any time it is ready to accept the initialization byte.

The high-byte/low-byte indicator (SO), bit 4 of the status byte, indicates data byte required by the Multimodule board. When bit 4 is set to 1, the Multimodule board is requesting the HIGH ORDER (most significant) BYTE of the data be presented on the bidirectional data bus. When bit 4 is set to 0, the Multimodule board is requesting the LOW ORDER (least significant) BYTE of data be presented on the data bus.

The utility test program error indicators, (S1 and S2), bits 5 and 6 of the status byte, report errors that occur during the execution of the firmware test program. Bit 5 set to 1 indicates a checksum error was detected on the checksum test that verifies the contents of the internal ROM of the UPI device. Bit 6 set to 1 indicates an error was detected during the RAM test that verifies the functionality of the internal RAM of the UPI device. Both bits 5 and 6 set to 0 indicates there were no detected errors during execution of the firmware test program.

The remaining three bits of the status byte are unused and should be ignored when checking status.

Software on the host iSBC microcomputer can use the IBF and SO flags in the status byte as a handshaking system when transferring data to the Multimodule board. The programming examples provided later in this chapter show methods of checking the status byte to determine the condition of the UPI device.

### 3-7. INTERRUPTS

The Multimodule board provides no means of issuing a direct interrupt request to the host iSBC microcomputer. Data transfer coordination between the host and the Multimodule board by the host software polling the Multimodule board status byte. The IBF, SO, and FO status bits from the UPI will give the required information to determine the status of the UPI device and the status of the last operation initiated on the Multimodule board. The SO bit indicates which of the two bytes of data is required by the Multimodule board.

#### NOTE

The host iSBC board software must check the IBF status bit before transferring each byte of data to the Multimodule board to ensure the input buffer can accept the next byte of data.

## PROGRAMMING INFORMATION

### 3-8. PROGRAMMING EXAMPLES

The programming examples in the following paragraphs are listed in the form of subroutines, each of which performs a programming function on the Multimodule board. Examples are included for issuing a RESET to the board, for issuing an initialization byte to the UPI on the board, and for issuing data to the UPI on the board. Included in the routines are typical status checking methods used to monitor the condition of the Multimodule board. The port addresses in the examples are listed with an "X" in the upper digit. Refer to the reference manual for the respective host iSBC microcomputer board to determine the value of "X" in the port address.

### 3-9. RESET PROGRAMMING EXAMPLE

The RESET command is issued to the Multimodule board by executing, on the host iSBC microcomputer, an OUT instruction that is directed to the status port address for the Multimodule board, as listed in Table 3-1. The RESET command clears the READY flag (F0) in the status byte by forcing the UPI to perform the power-on RESET firmware routine. Table 3-2 lists a typical RESET subroutine, however the port addresses may change depending on the iSBX connector and the type of host board used.

Table 3-2. Typical RESET Subroutine

```
;This routine issues a RESET command to the Multimodule board.
;Uses-A, STATUS; Destroys-Nothing.

      PUBLIC   RESET
      STATUS   EQU       XIH      ;Defines status port address
RESET:  OUT     STATUS     ;Write to the UPI status port,
                                ;contents of A register is not
                                ;important

      RET
```

### 3-10. INITIALIZATION WORD PROGRAMMING EXAMPLE

Table 3-3 contains a typical subroutine for sending an initialization word to the UPI. The port addresses shown in the example in Table 3-3 may have to be changed for the application, depending on the type of host iSBC microcomputer used.

Table 3-3. Typical Initialization Word Routine

```

;INIT outputs an initialization word from A to the 8041 UPI port upon
;recognition of the READY flag.
;Uses-A, STATUS, RYMASK: Destroys-Nothing.

PUBLIC INIT

STATUS EQU XIH ;Defines status port address
RDMASK EQU 4 ;Defines READY flag mask
DATAD EQU XOH ;Defines Data port address

INIT: IN STATUS ;Read UPI status byte
      ANI RYMASK ;Check for UPI READY status
      JZ INIT ;Waiting for READY status
      MVI A,OFH ;Load initialization word into A.
              ;Set UPI to Voltage-only mode and 8
              ;Channel scan
      OUT DATAD ;Send initialization word to data
              ;Port
      RET
    
```

3-11. WRITE DATA PROGRAMMING EXAMPLE

Table 3-4 lists a typical subroutine for sending data to the UPI on the Multimodule board. The port addresses may have to be changed to fit the application, depending on the requirements of the host iSBC microcomputer.

Table 3-4. Typical Data Output Subroutine

```

;ODATA outputs data from A to the UPI on the Multimodule board.
;Uses-A, STATUS, IBMASK, BASAD; Destroys-Nothing.

PUBLIC ODATA

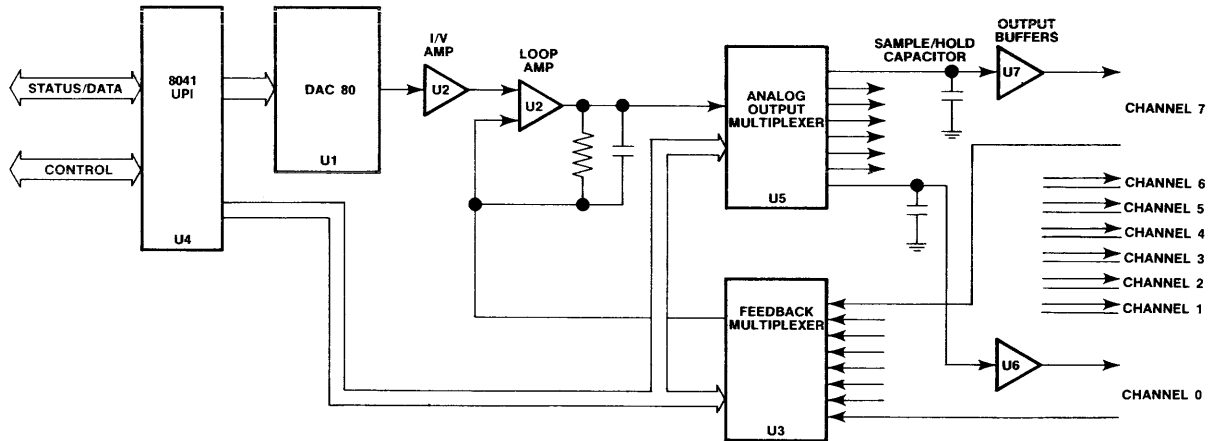
STATUS EQU XIH ;Defines status port address
BASAD EQU XOH ;Defines data port address
IBMASK EQU 2 ;Defines Input-Buffer-Full flag mask

ODATA: IN STATUS ;Read UPI status byte
      ANI IBMASK ;Mask for IBF bit of status
      JNZ ODATA ;Wait for IBF not full
      MOV A,B ;Load data byte from B register
              ;into A
      OUT BASAD ;Send the data in A to the UPI
      RET
    
```

## CHAPTER 4. PRINCIPLES OF OPERATION

### 4-1. INTRODUCTION

This chapter provides a functional description of the interface signals and a detailed circuit analysis for the iSBX 328 Analog Output Multimodule Board. The functional description of the board includes details on the operation of each of the major components on the board. Figure 4-1 shows a functional block diagram of the interaction between the major components of the Multimodule board.



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Figure 4-1. iSBX™ 328 Board Functional Block Diagram

## PRINCIPLES OF OPERATION

### 4-2. iSBX™ BUS INTERFACE SIGNAL DESCRIPTION

Programmed control of the iSBX 328 Analog Output Multimodule Board is achieved by controlling the signals that interface to and from the Multimodule board via the iSBX bus connector. The iSBX bus signals that interact with the Multimodule board and their functions are detailed in the following paragraphs.

RESET (Reset) - This active high signal, when asserted to the Multimodule board, resets the 8041 UPI device on the board. Since the UPI device operates from the free-running clock, it will immediately begin program execution when the RESET signal is removed. Notice that the RESET signal is inverted by Q9, R15, and R16 on the Multimodule board to create a negative-true RESET signal, as required by the UPI device.

MDO-MD7 (Bidirectional Data Bus) - These eight bidirectional data lines provide a means of transferring commands, status, and data between the UPI device on the Multimodule board and the host iSBC microcomputer.

IORD/ (Read Command) - This active low signal is generated by the host iSBC microcomputer as a command to the Multimodule board to input data via the bidirectional data bus (MDO-MD7) to the host. The IORD/ signal enables the UPI device to input data from the bidirectional data bus into an internal Input Buffer Register or to output data from an internal Status Register onto the bidirectional data bus.

IOWRT/ (Write Command) - This active low signal is generated by the host iSBC microcomputer as a command to the Multimodule board to accept data present on the bidirectional data bus. The IOWRT/ signal causes the UPI device to accept data into its Data Bus Buffer register from the bidirectional data bus.

MCS0/ (Select) - MCS0/ is an active low input signal to the Multimodule board to enable the board to accept either an IORD/ or IOWRT/ command from the host iSBC microcomputer board.

MA0 (Function Selector) - This active high input from the host iSBC microcomputer, in conjunction with the IORD/ and IOWRT/ signals, selects whether the data byte on the bidirectional bus is to be treated as data or command input.

### 4-3. FUNCTIONAL DESCRIPTION

The functional description is based upon the functional block diagram shown in figure 4-1. Each functional block in the figure is explained in detail in the following paragraphs.

## PRINCIPLES OF OPERATION

### 4-4. 8041 UNIVERSAL PERIPHERAL INTERFACE

The 8041 UPI device (U4) is a single-chip microcomputer that contains 1024 bytes of program memory, 64 bytes of data memory, 18 I/O lines, an 8-bit CPU, an event timer, and a clock oscillator within a single 40-pin LSI package. The UPI is driven with the dedicated on-board clock (Y1) at a rate of 6 MHz. The firmware supplied with the UPI enables it to operate as a controller in accepting commands from the host iSBC microcomputer and performing data transfers to the analog application. Data from the host iSBC microcomputer board is translated within the UPI into a 12-bit DAC word and a 4-bit multiplexer control word from port 1 and port 2 of the UPI device. The data transfer handshaking is performed via the Input Buffer Full (IBF) and the High/Low-Byte (SO) indicators within the status byte. More information on the programming of the UPI device is contained in chapter 3 of this text.

### 4-5. DIGITAL-TO-ANALOG CONVERTER

The DAC (U1) converts 12 bits of digital input code to a proportional current output from pin 15. The DAC data input lines are active LOW and cause a digital hexadecimal data input of FFFH to generate a zero current flow output from pin 15 of the DAC. By the same means, the DAC converts an input of 000 into a full scale current flow output. The magnitude of the full scale current flow is influenced by the reference voltage on pin 16, but will generally range about -2 mA (the "minus" signifies that the DAC is operating as a current sink). The DAC contains internal resistors that perform current-to-voltage translations and that perform bipolar current offsetting functions.

### 4-6. CURRENT-TO-VOLTAGE AMPLIFIER

The current-to-voltage translator is completed by amplifier U2 (pins 1, 2, and 3) and by two resistors internal to the DAC.

### 4-7. LOOP AMPLIFIER

The loop amplifier, U2 pins 5, 6, and 7, is used to provide feedback for the data output operation when the board is operating in either the voltage output or the current loop output mode. The feedback loop corrects for offsets and temperature effects induced by the various on-board devices in the path of the output signal.

## PRINCIPLES OF OPERATION

### 4-8. FREQUENCY COMPENSATOR

The frequency compensation logic consists of capacitors C2, C3, and C9 and resistors R8 and R9. Together these devices form a feedback control network that allows a dc gain of approximately 20. The network controls the frequency response of the output to ensure a stable gain despite small variances in the sample-and-hold capacitance, the multiplexer resistance, and the load capacitance.

### 4-9. OUTPUT MULTIPLEXER

The output multiplexer (U5) gates the analog output data from U2 to one of eight channels, as selected by the UPI device. The multiplexer acts as a low resistance switch in providing an analog data signal to the sample-and-hold capacitors. Each channel is selected with a binary decode of the three least significant bits (bits 1, 2, and 3) of the port 2 output from the UPI device. The bit 0 output from the UPI (port 2) is used to enable the output multiplexer for operation.

### 4-10. BUFFER AMPLIFIERS

The buffer amplifiers (U6 and U7) are designed to supply a high impedance when providing data to the sample-and-hold capacitors to prevent a quick voltage decay when the channel is not selected. Depending on the jumper configuration, the buffers can operate as a unity-gain buffer amplifier in voltage output mode or as a 4 to 20 mA current converter, maintaining a constant voltage drop across the current-sampling resistors (R18 through R25). The two resistors and capacitor on each channel provide isolation from capacitive loads.

### 4-11. FEEDBACK MULTIPLEXER

The feedback multiplexer (U3) selects an output channel synchronous with the channel selection performed by the output multiplexer (U5); that is, when one channel is selected to receive output, it is also selected to provide feedback. Feedback from the channel enters the multiplexer on one of the eight inputs. If selected, the input is gated through the multiplexer and out pin 12. The feedback current then returns to the loop amplifier (U2) to provide loop error correction.

### 4-12. VOLTAGE-TO-CURRENT CONVERTER

The voltage-to-current converter consists of transistors Q1 through Q8 and resistors R18 through R25. These components work together to convert the multiplexer voltage into a related current of 4 to 20 mA. A compliance voltage of 12 to 40 volts is acceptable, but current loop loads must be provided for voltages greater than 12 volts.



## CHAPTER 5. SERVICE INFORMATION

### 5-1. INTRODUCTION

This chapter provides a list of replaceable parts, service diagrams, adjustments, and service and repair assistance instructions of the iSBX 328 Analog Output Multimodule Board.

### 5-2. SERVICE AND REPAIR ASSISTANCE

United States customers can obtain service and repair assistance by contacting the Intel Product Service Center in Phoenix, Arizona. Customers outside the United States should contact their sales source (Intel Sales Office or Authorized Distributor) for service information and repair assistance.

Before calling the Product Service Center, you should have the following information available:

- a. Date you received the product.
- b. Complete part number of the product (including dash number). This number is usually silk-screened onto the component side of the board.
- c. Serial number of product. This number is usually stamped onto the component side of the board.
- d. Shipping and billing addresses.
- e. Purchase order number for billing purposes if your Intel product warranty has expired.
- f. Extended warranty agreement information, if applicable.

Use the following numbers for contacting the Intel Product Service Center:

Regional Telephone Numbers:

Western Region: 602-869-49851  
Midwest Region: 602-869-4392  
East Region: 602-869-4045  
International: 602-869-4391



TWX Number:

910-951-1330

## SERVICE INFORMATION

Always contact the Product Service Center before returning a product to Intel for repair. You will be given a repair authorization number, shipping instructions, and other important information which will help Intel provide you with fast, efficient service. If you are returning the product because of damage sustained during shipment or if the product is out of warranty, a purchase order is required before Intel can initiate the repair.

In preparing the product for shipment to the Repair Center, use the original factory packing material, if possible. If this material is not available, wrap the product in cushioning material such as Air Cap TH-240, manufactured by the Sealed Air Corporation, Hawthorne, N.J. Then enclose in a heavy duty corrugated shipping carton, and label "FRAGILE" to ensure careful handling. Ship only to the address specified by the Product Service Center Personnel.

### 5-3. ADJUSTMENT PROCEDURES

The adjustments for the iSBX 328 Analog Output Multimodule Board include facilities to allow the user to perform 3 adjustments; current loop offset, DAC offset, and voltage gain. The calibration procedure for each adjustment differs slightly, depending on whether the Multimodule board is configured for a voltage output mode application of a current loop output mode application or a current loop output mode application. The procedures for each adjustment are outlined in the following paragraphs and assume that there is an offset adjustment subroutine (DACOFF) and a range adjustment subroutine (DACRNG), similar to those listed in Appendix A, resident within the program begin executed on a microcomputer development system. Each Multimodule board is adjusted at the factory, however, the boards should be readjusted whenever reconfiguration occurs. The calibration procedure is preceded by a list of test equipment required to perform the calibration.

#### NOTE

When performing the adjustments for a board containing a mixed configuration (both voltage output channels and current loop channels) or for a board containing only voltage output channels, follow the adjustment procedure as described for the voltage output mode. Adjust the board as described for the current loop output mode only when all channels on the board are configured to operate as current loop channels.

## SERVICE INFORMATION

### 5-4. TEST EQUIPMENT REQUIRED

The only test equipment required to adjust the gain and offset for the Multimodule board is a Digital Voltmeter (DVM) with a voltage range of 0 to 10 volts and an accuracy of  $\pm 0.005\%$  or better. The procedure listed here also requires the use of an Intel microcomputer development system to provide an operating system for running the calibration programs and to provide power for the Multimodule board and the host iSBC microcomputer.

### 5-5. PRELIMINARY ADJUSTMENT PROCEDURE

The first step of the calibration procedure is to check the voltage levels for the dc supply voltages. The dc supply voltages are listed in Table 5-1 and may be verified on the Multimodule board at the capacitors listed. If any of the power sources are out of tolerance, they should be readjusted before the calibration procedure is performed.

Table 5-1. Power Supply Voltage Checkpoints

Supply	Tolerance	Voltmeter Connection on Multimodule Board
+12V	$\pm 5\%$	Across C28
-12V	$\pm 5\%$	Across C27
+ 5V	$\pm 5\%$	Across C26

NOTE: Refer to Figure 5-1 to locate capacitors

### 5-6. VOLTAGE OUTPUT MODE OFFSET ADJUSTMENT

Connect the positive lead of the DVM to connector J1 pin-4 and the negative lead to connector J1 pin-3. CALL the offset and adjustment subroutine (DAC-OFF in Appendix A) and adjust variable resistor R1 for either 0.0000 volts (unipolar operation) or -5.0000 volts (bipolar operation).

### 5-7. VOLTAGE OUTPUT MODE RANGE ADJUSTMENT

Connect the DVM as for the offset adjustment (positive to connector J1 pin-4, negative to J1 pin-3) and CALL the offset and adjustment subroutine (DAC-RNG in Appendix A) and adjust variable resistor R1 for either 4.9976 volts (unipolar operation) or -4.9988 volts (bipolar operation).

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5-8. CURRENT LOOP OUTPUT MODE GAIN ADJUSTMENT

Connect positive lead of the DVM to the E36 and the negative lead to connector J1 pin-3. CALL the offset adjustment subroutine (DACOFF in Appendix A) and adjust variable resistor R3 to attain a reading of 0.6250 volts. If R3 does not carry the adjustment to 0.6250 volts, use resistor R1 to complete the adjustment.

5-9. CURRENT LOOP MODE OUTPUT RANGE ADJUSTMENT

Connect the DVM as for the offset adjustment (positive lead to the E36 and negative lead to connector J1 pin-3), and CALL the range adjustment subroutine (DACRNG in Appendix A). Adjust variable resistor R2 until a reading of 3.1244 volts is attained.

5-10. REPLACEABLE PARTS

Table 5-3 provides a list of replaceable parts for the Multimodule board. Table 5-2 identifies and locates the manufacturers specified in the MFR CODE column of Table 5-3. Intel parts that are available on the open market are listed in the MFR CODE column as "COML". Every effort should be made to procure these parts from a local (commercial) distributor.

Table 5-2. Manufacturer Codes

Mfr. Code	Manufacturer	Address
AD	Analog Devices	Santa Clara, CA
BEC	Beckman Instruments	Cedar Grove, NY
CCC	Crystek Crystal Corp.	Ft. Myers, FL
EMC	EMC Technology, Inc.	Cherry Hill, NJ
HAR	Harris Semiconductor	Dallas, TX
INTEL	Intel Corp.	Santa Clara, CA
MOT	Motorola	Phoenix, AZ
NAT	National Semiconductor	Santa Clara, CA
VIK	Viking Connector, Inc.	Chatsworth, CA
OBD	Order by description, any commercial (COML) source	

SERVICE INFORMATION

Table 5-3. Replaceable Parts

Reference Designator	Description	Mfr. Part No.	Mfr. Code	Qty
U4	IC, Universal Peripheral Interface	8041A	INTEL	11
U6,U7	IC, Quad BI FET Linear Op Amp	LF-347BN	NAT	2
U2	IC, Quad Linear Op Amp	LF-353BN	NAT	1
U3,U5	IC, Analog Multiplexer	H1-1818A*	HAR	2
U1	IC, Digital-to-Analog Converter	DAC-80Z	AD	1
VR1	Diode, Zener 1N4576	1N4576	MOT	1
Q9	Transistor, PNP, 2N4403	OBD	COML	1
Q1-Q8	Transistor, NPN, Darlington, 2N6427	OBD	COML	8
Y1	Crystal, 6 MHz	CY6B	CCC	1
P1	Connector, 36-pin	68-357	VIK	1
	Socket, 20-pin, SIP	7195-295-5	EMC	2
	Socket, 12-pin, SIP	7195-295-5	EMC	2
	Socket, 8-pin, SIP	7195-295-5	EMC	2
	Socket, 7-pin, SIP	7195-295-5	EMC	4
E1-E3, E13-E37	Wirewrap stake pin	87022-1	AMP	33
	Shorting plugs	53053-2	AMP	10
RP1,RP2	Resistor pack, 1K, 8-pin, SIP <u>+2%</u>	764-3-R1K	BEC	2
RP3,RP4	Resistor pack, 4.7K, 8-pin, SIP, <u>+2%</u>	764-3-R4.7K	BEC	2
RP5,RP6	Resistor pack, 33 ohm, 8-pin, SIP, <u>+2%</u>	764-3-R33	BEC	2
R1,R2	Resistor, adjustable, 20K	OBD	COML	2
R3	Resistor, adjustable, 200 ohm	OBD	COML	1
R4	Resistor, 1.6K, 0.1%, 1/20 W	OBD	COML	1
R5	Resistor, 464K, 1%, 1/8 W	OBD	COML	1
R7,R17	Resistor, 1.1K, 5%, 1/4 W	OBD	COML	1
R8	Resistor, 20K, 5%, 1/4 W	OBD	COML	1
R6,R12	Resistor, 196K, 1%, 1/8W	OBD	COML	1
R9	Resistor, 3.6K, 5%, 1/4 W	OBD	COML	1
R15,R16	Resistor, 10K, 5%, 1/4 W	OBD	COML	2
R10,R13, R14	Resistor, 10K, 0.1%, 1/20 W	OBD	COML	3
R11	Resistor, 39.2K, 1%, 1/8 W	OBD	COML	2
R18-R25	Resistor, 156.25 ohm, 0.02%, 1/20 W	OBD	COML	8
C1	Capacitor, 0.1 uF, +80 -20%, 50V, ceramic	OBD	COML	1
C2	Capacitor, 68 pF, 10%, 50V, ceramic	OBD	COML	1
C3,C8	Capacitor, 390 pF, <u>+10%</u> , 50V, ceramic	OBD	COML	2
C5	Capacitor, 0.01 uF, +80 -20%, 50V, ceramic	OBD	COML	1
C9	Capacitor, 220 pF, <u>+10%</u> , 50V, ceramic	OBD	COML	1

SERVICE INFORMATION

Table 5-3. Replaceable Parts (continued)

Reference Designator	Description	Mfr. Part No.	Mfr. Code	Qty
C11,C12	Capacitor, 22 pF, <u>+10%</u> , 50V, ceramic	OBD	COML	2
C4,C6,C7, C13-C15	Capacitor, 0.47uF, +80 -20%, 50V, ceramic	OBD	COML	6
C10,C22-C24, C30-C33	Capacitor, 0.1 uF, +80 -20%, 50V, ceramic	OBD	COML	8
C16-C21, C25,C29	Capacitor, 0.22 uF, <u>+10%</u> , 50V ceramic	OBD	COML	8
C27,C28	Capacitor, 15 uF, <u>+20%</u> , 20V, tant.	OBD	COML	2
C26	Capacitor, 33 uF, <u>+20%</u> , 10V, tant.	OBD	COML	1
C34-C41	Capacitor, 470 pF, <u>+10%</u> , 50V, ceramic	OBD	COML	8
<p>*Primary Source Component. The board may require a configuration jumper change if the make of the component which the factory installed in the board is changed. The jumper selects between A +5 Vdc or ground input to Pin-2 of the multiplexer. Check the manufacturer's specifications to determine the input requirements.</p>				

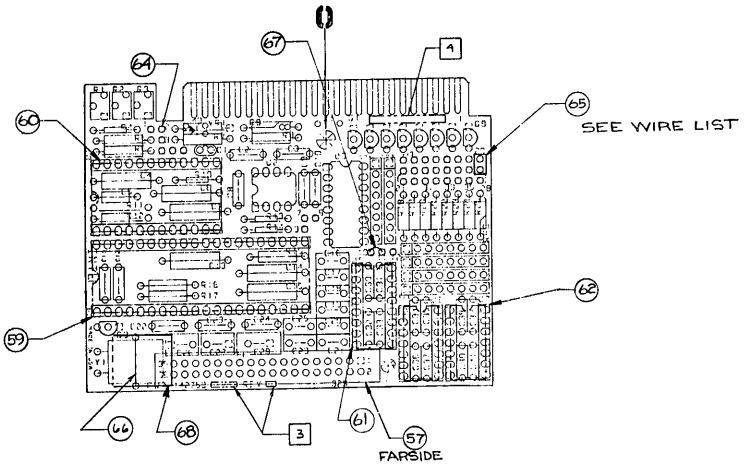
5-11. SERVICE DIAGRAMS

The parts location diagram and schematic diagrams for the Multimodule board are provided in Figures 5-1 and 5-2, respectively. On the schematic diagram, a signal mnemonic that ends with a slash (e.g., MSCO/) is active LOW. Conversely, a signal mnemonic without the slash (e.g., OPTO) is active HIGH.

DWG NO. 142759 SH 1 REV 5

ZONE	REV	DESCRIPTION	DFT	CHK	DATE	APPROVED
A		ECO 40-2153				
B		ECO 40-2303				
C		ECO 40-2409				
D		ECO 40-3137				

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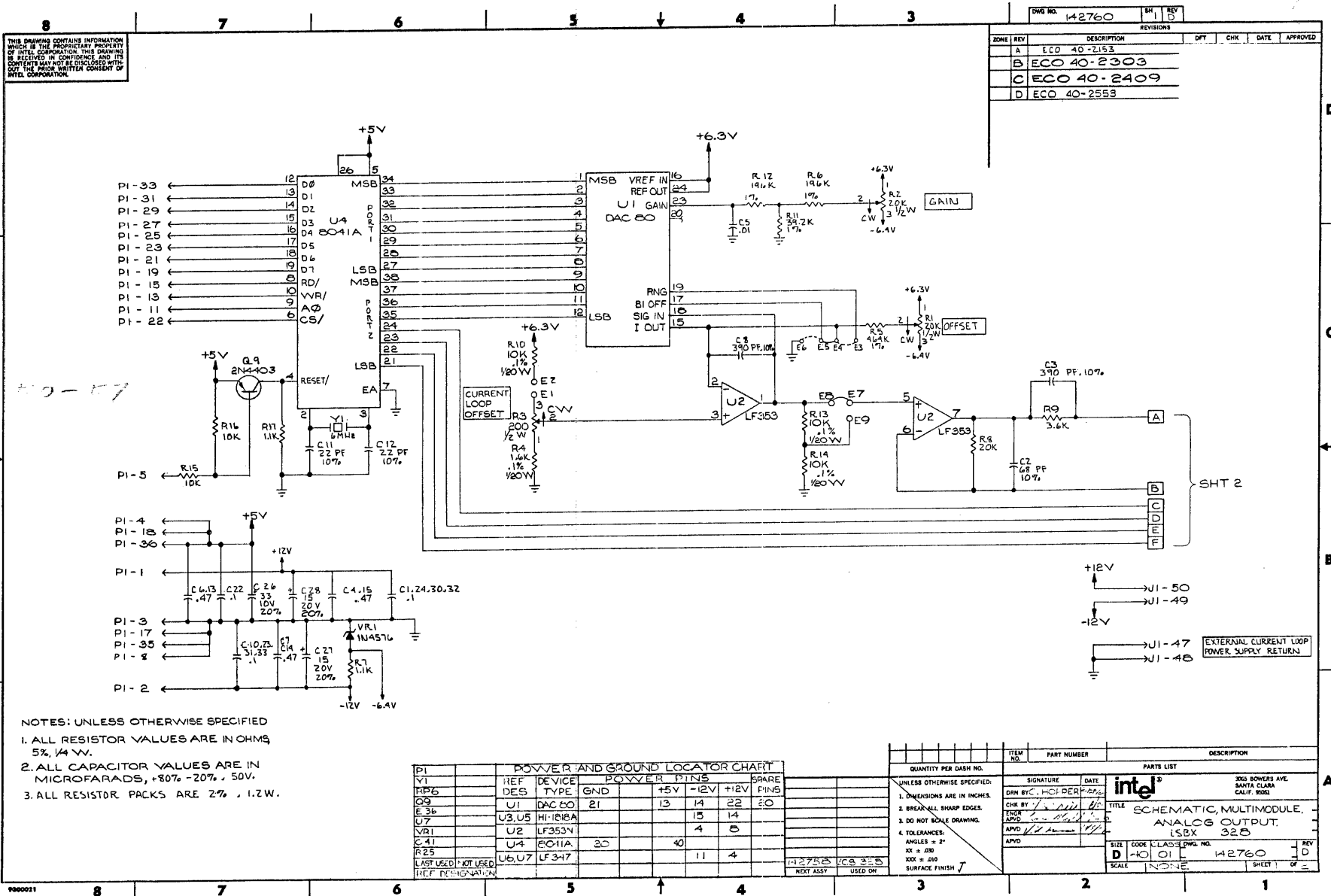
- NOTES: UNLESS OTHERWISE SPECIFIED
- ASSEMBLY PART NUMBER IS 142753-003 THIS DOCUMENT, PL AND WL ARE TRACKING DOCUMENTS.
  - WORKMANSHIP PER. 99-0007-001.
  - MARK ASSEMBLY DASH NUMBER AND REVISION LEVEL WITH CONTRASTING PERMANENT COLOR, .12 HIGH, NON-CONDUCTIVE, APPROX. WHERE SHOWN.
  - MARK VENDOR I.D. WITH PERMANENT CONTRASTING COLOR, .12 HIGH, NON-CONDUCTIVE, APPROX. WHERE SHOWN.
  - PLACE INSULATING TAPE (ITEM 6B) UNDER CRYSTAL (Y1).
  - REMOVED

ITEM NO.	PART NUMBER	DESCRIPTION
		QUANTITY PER DASH NO.
		UNLESS OTHERWISE SPECIFIED:
		1. DIMENSIONS ARE IN INCHES.
		2. BREAK ALL SHARP EDGES.
		3. DO NOT SCALE DRAWING.
		4. TOLERANCES:
		ANGLES ± .1°
		XXX ± .010
		SURFACE FINISH 7
		DATE 7-23-90
		SIGNATURE [Signature]
		CHK BY [Signature]
		APVD [Signature]
		APVD [Signature]
		TITLE PRINTED WIRING ASSEMBLY
		LSBX 328
		SCALE NONE
		REV D
		INCL. NO. 142759
		SHEET 1 OF 1

Figure 5-1. LSBX™ 328 Analog Output Multimodule™ Board  
Parts Location Diagram

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Figure 5-2. ISBX™ 328 Analog Output Multimodule™ Board Schematic Diagram



SERVICE INFORMATION



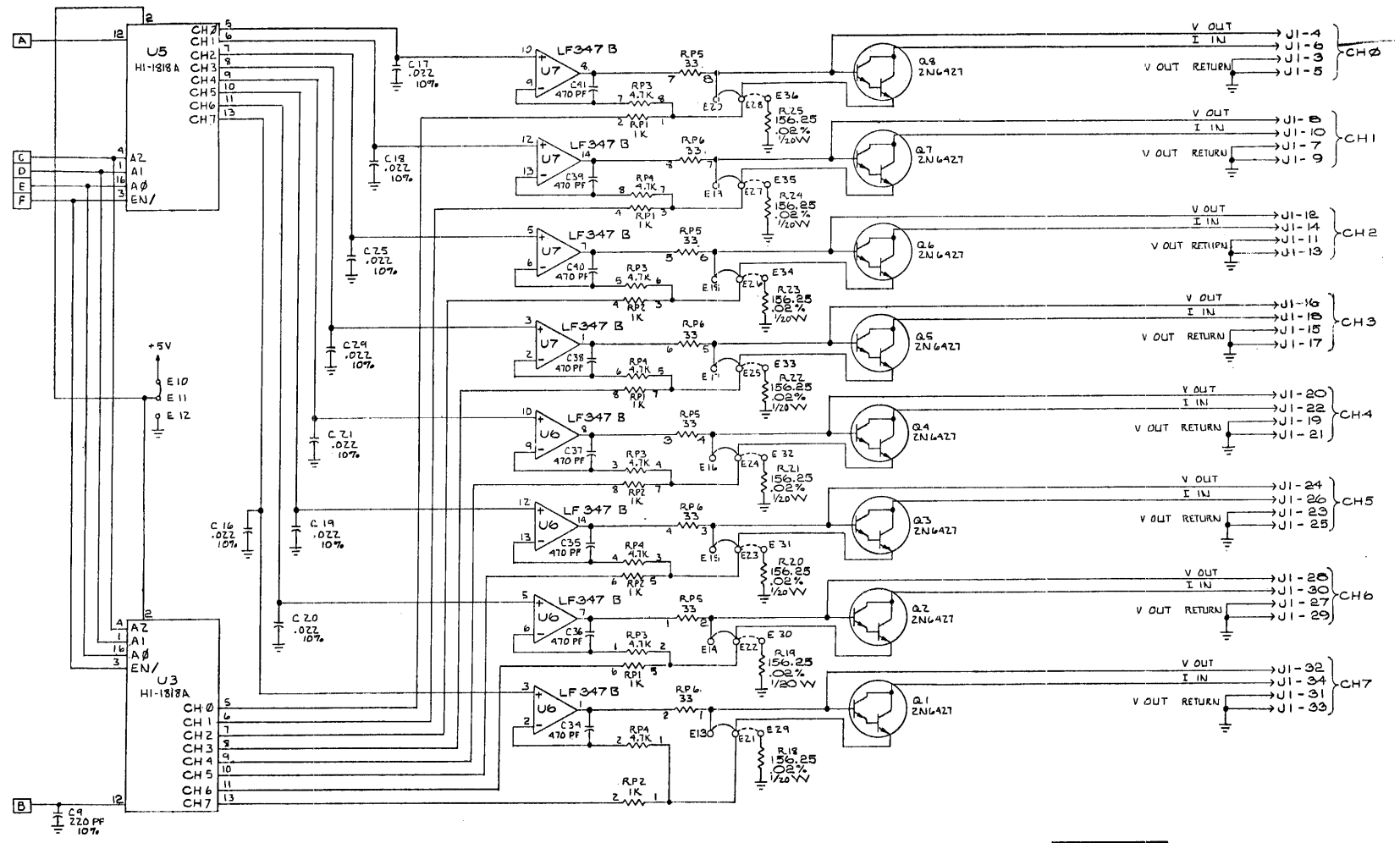
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DWG NO. 14270 SH. 2 OF 2

ZONE	REV	DESCRIPTION	DPT	CHK	DATE	APPROV
SEE SHEET ONE						

5-9

SERVICE INFORMATION



DRAWN	O. HOPPER	SIZE	D	CODE	CS	DWG NO.	14270	REV	D
ISSUED		SCALE	NONE						

APPENDIX A. ADJUSTMENT PROGRAMMING EXAMPLES

The programs listed in the following text are designed for use in an Intel microcomputer development system to allow calibration of the iSBX 328 Analog Output Multimodule Board. Table A-1 contains a range calibration program and Table A-2 contains an offset calibration program. Calibration instructions are listed in Chapter 5 of the text.

Table A-1. RANGE Adjustment

<p>This table contains subroutines for use in performing the RANGE adjustment for the iSBX 328 Analog Output Multimodule Board when installed into the J6 Multimodule Connector (closest to the center) of a host iSBC 80/24 board. To configure for another Multimodule Connector or host, modify the port addresses as specified in the hardware reference manual for the respective iSBC microcomputer board.</p> <p>The DACRNG routine selects channel 0 and initializes it for operation. Data to be output on the channels is placed into the B register. The OUTRDY routine checks the status of the UPI and outputs the data contained in the B register successively to each channel selected. While the program is operating, the RANGE for the DAC may be adjusted as detailed in Chapter 5 of the text.</p> <p>The software reset at the start of the DACRNG routine is not typical for data transfer. It is included here to assure accurate range adjustment.</p>			
	PUBLIC	OUTRDY,	DACRNG
	STATUS	EQU	0F1H ;Status Port Address
	DATA	EQU	0FOH ;Data Port Address
	IBMASK	EQU	02H ;IBF Mask
	CSEG		
DACRNG:	OUT	STATUS	;Software Reset
	MVI	B, 0BH	;Select number of channels scanned
	CALL	OUTRDY	;Output when UPI ready
	MVI	B, 0FOH	;Select channel 0, LOW BYTE-FOH
	CALL	OUTRDY	;Output when UPI Ready
	MVI	B, 0FFH	;Select HIGH BYTE - FFH
	CALL	OUTRDY	;Output when UPI ready
	RET		
OUTRDY:	IN	STATUS	;Read status byte
	ANI	IBMASK	;Check for iBF = 1
	JNZ	OUTRDY	;Yes, check again
	MOV	A, B	;No, get data
	OUT	DATA	;Send data
	RET		

ADJUSTMENT PROGRAMMING EXAMPLES

Table A-2. OFFSET Adjustment

This table contains subroutines for use in performing the DAC OFFSET Adjustment for the iSBX 328 Analog Output Multimodule Board when installed into the J6 Multimodule Connector on a host iSBC 80/24 board. To configure for another Multimodule Connector or another host, modify the port addresses as specified in the hardware reference manual for the respective iSBC microcomputer board.

The DACOFF routine selects channels 0 for operation. Data to be output on the channels is placed into the B register. The OUTRDY routine then checks the status of the UPI and outputs the data. While the program is operating, the OFFSET for the DAC may be adjusted as detailed in Chapter 5 of the text.

```

PUBLIC  OUTRDY, DACOFF
STATUS EQU 0F1H    ;Status Port
DATA   EQU 0FOH    ;Data Port
IBMASK EQU 02H     ;IBF Mask

CSEG

DACOFF:  OUT    STATUS    ;Software Reset
         MVI    B,OBH    ;Select number of channels to scan
         CALL   OUTRDY    ;Output when UPI ready

         MVI    B,0      ;Select channel 0.
         CALL   OUTRDY    ;Output LOW BYTE data = 0
         CALL   OUTRDY    ;Output HIGH BYTE data = 0
         RET

OUTRDY:  IN     STATUS    ;Read status byte
         ANI    IBMASK    ;Check for IBF = 1
         JNZ    OUTRDY    ;Yes, check again
         MOV    A,B        ;No, prepare data
         OUT    DATA     ;Send data
         RET
    
```

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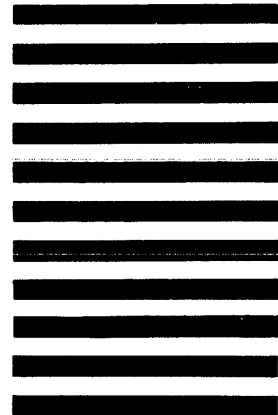
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